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Kind regards,

Team Nexperia

# 74AHC1G79; 74AHCT1G79

Single D-type flip-flop; positive-edge trigger

Rev. 6 — 23 September 2014

Product data sheet

## 1. General description

74AHC1G79 and 74AHCT1G79 are high-speed Si-gate CMOS devices. They provide a single positive-edge triggered D-type flip-flop.

Information on the data input is transferred to the Q output on the LOW-to-HIGH transition of the clock pulse. The D input must be stable one set-up time prior to the LOW-to-HIGH clock transition for predictable operation.

The AHC device has CMOS input switching levels and supply voltage range 2 V to 5.5 V.

The AHCT device has TTL input switching levels and supply voltage range 4.5 V to 5.5 V.

## 2. Features and benefits

- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- SOT353-1 and SOT753 package options
- ESD protection:
  - ◆ HBM JESD22-A114F: exceeds 2000 V
  - ◆ MM JESD22-A115-A: exceeds 200 V
  - ◆ CDM JESD22-C101C: exceeds 1000 V
- Specified from -40 °C to +125 °C

## 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AHC1G79GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74AHCT1G79GW				
74AHC1G79GV	-40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74AHCT1G79GV				



## 4. Marking

Table 2. Marking codes

Type number	Marking <sup>[1]</sup>
74AHC1G79GW	AP
74AHC1G79GV	A79
74AHCT1G79GW	CP
74AHCT1G79GV	C79

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

## 5. Functional diagram

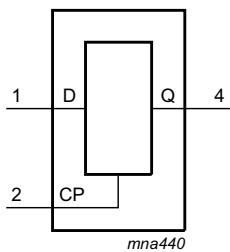


Fig 1. Logic symbol

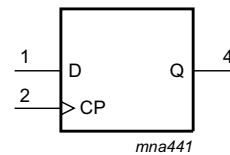


Fig 2. IEC logic symbol

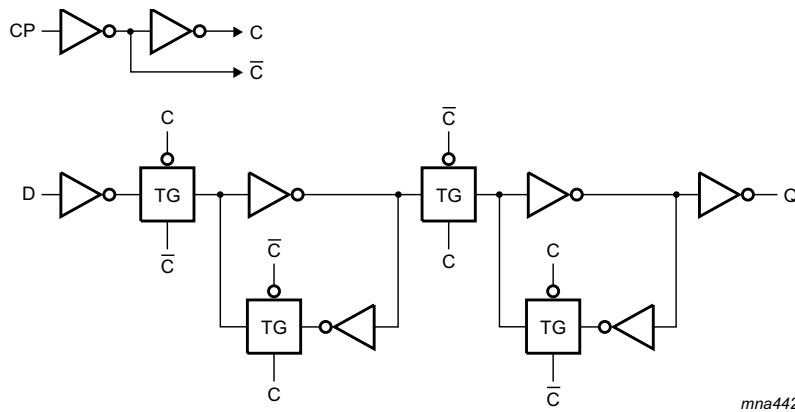


Fig 3. Logic diagram

## 6. Pinning information

### 6.1 Pinning

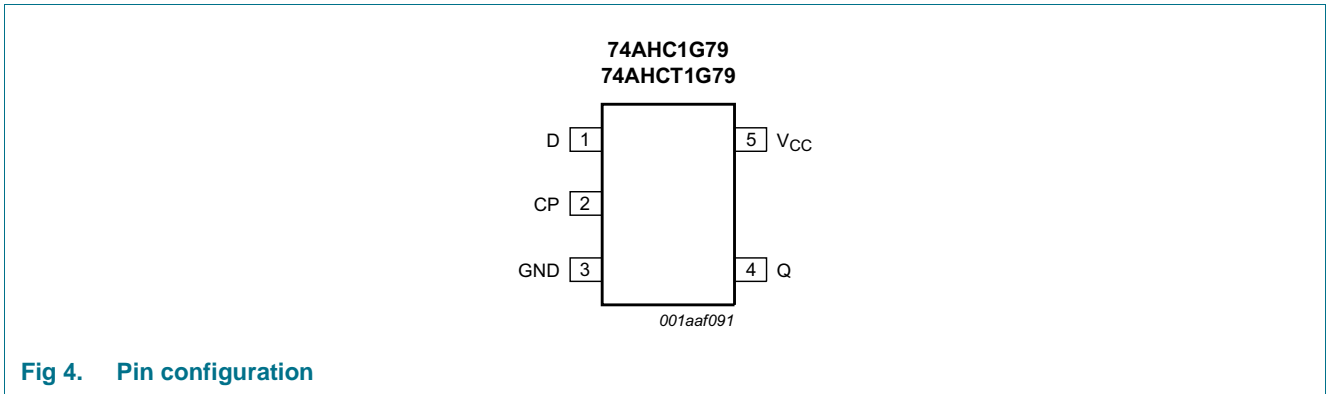


Fig 4. Pin configuration

### 6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
D	1	data input
CP	2	clock pulse input
GND	3	ground (0 V)
Q	4	data output
V <sub>CC</sub>	5	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Inputs		Output
CP	D	Q + 1
↑	L	L
↑	H	H
L	X	Q

- [1] H = HIGH voltage level;  
 L = LOW voltage level;  
 ↑ = LOW-to-HIGH CP transition;  
 X = don't care;  
 Q + 1 = state after the next LOW-to-HIGH CP transition.

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		-0.5	+7.0	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V	-20	-	mA
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V <a href="#">[1]</a>	-	$\pm 20$	mA
$I_O$	output current	$-0.5$ V $< V_O < V_{CC} + 0.5$ V	-	$\pm 25$	mA
$I_{CC}$	supply current		-	75	mA
$I_{GND}$	ground current		-75	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C <a href="#">[2]</a>	-	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For both TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74AHC1G79			74AHCT1G79			Unit
			Min	Typ	Max	Min	Typ	Max	
$V_{CC}$	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 3.3$ V $\pm 0.3$ V	-	-	100	-	-	-	ns/V
		$V_{CC} = 5.0$ V $\pm 0.5$ V	-	-	20	-	-	20	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>For type 74AHC1G79</b>										
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0$ V	1.5	-	-	1.5	-	1.5	-	V
		$V_{CC} = 3.0$ V	2.1	-	-	2.1	-	2.1	-	V
		$V_{CC} = 5.5$ V	3.85	-	-	3.85	-	3.85	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0$ V	-	-	0.5	-	0.5	-	0.5	V
		$V_{CC} = 3.0$ V	-	-	0.9	-	0.9	-	0.9	V
		$V_{CC} = 5.5$ V	-	-	1.65	-	1.65	-	1.65	V

**Table 7. Static characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	V
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.58	-	-	2.48	-	2.40	-	V
		I <sub>O</sub> = -8.0 mA; V <sub>CC</sub> = 4.5 V	3.94	-	-	3.8	-	3.70	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I <sub>O</sub> = 8.0 mA; V <sub>CC</sub> = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	1.0	-	10	-	40	μA
C <sub>I</sub>	input capacitance		-	1.5	10	-	10	-	10	pF
<b>For type 74AHCT1G79</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -50 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -8.0 mA	3.94	-	-	3.8	-	3.70	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 50 μA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 8.0 mA	-	-	0.36	-	0.44	-	0.55	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	1.0	-	10	-	40	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = 3.4 V; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C <sub>I</sub>	input capacitance		-	1.5	10	-	10	-	10	pF

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

$GND = 0\text{ V}$ ;  $t_r = t_f = \leq 3.0\text{ ns}$ . For test circuit see [Figure 6](#). For waveforms see [Figure 5](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>For type 74AHC1G79</b>										
$t_{pd}$	propagation delay	CP to Q <a href="#">[1]</a>								
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ <a href="#">[2]</a>								
		$C_L = 15\text{ pF}$	-	4.9	8.4	1.0	9.8	1.0	11.5	ns
		$C_L = 50\text{ pF}$	-	6.9	12.0	1.0	14.0	1.0	15.5	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ <a href="#">[3]</a>								
		$C_L = 15\text{ pF}$	-	3.5	5.6	1.0	7.0	1.0	8.0	ns
		$C_L = 50\text{ pF}$	-	5.1	8.0	1.0	10.0	1.0	11.0	ns
$t_{su}$	set-up time	D to CP	3.0	1.0	-	3.0	-	4.0	-	ns
$t_h$	hold time	D to CP	+2.0	-1.0	-	2.0	-	3.0	-	ns
$t_W$	pulse width	clock HIGH or LOW	3.0	-	-	3.0	-	4.0	-	ns
$f_{max}$	maximum frequency		90	-	-	90	-	70	-	MHz
$C_{PD}$	power dissipation capacitance	per buffer; $C_L = 50\text{ pF}$ ; $f = 1\text{ MHz}$ ; $V_I = GND\text{ to }V_{CC}$ <a href="#">[4]</a>	-	15	-	-	-	-	-	pF
<b>For type 74AHCT1G79</b>										
$t_{pd}$	propagation delay	CP to Q <a href="#">[1]</a>								
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ <a href="#">[3]</a>								
		$C_L = 15\text{ pF}$	-	3.5	5.0	1.0	6.0	1.0	8.0	ns
		$C_L = 50\text{ pF}$	-	5.0	8.0	1.0	10.0	1.0	11.0	ns
$t_{su}$	set-up time	D to CP	3.0	1.0	-	3.0	-	4.0	-	ns
$t_h$	hold time	D to CP	+2.0	-1.0	-	2.0	-	3.0	-	ns
$t_W$	pulse width	clock HIGH or LOW	3.0	-	-	3.0	-	4.0	-	ns
$f_{max}$	maximum frequency		90	-	-	90	-	70	-	MHz
$C_{PD}$	power dissipation capacitance	per buffer; $C_L = 50\text{ pF}$ ; $f = 1\text{ MHz}$ ; $V_I = GND\text{ to }V_{CC}$ <a href="#">[4]</a>	-	16	-	-	-	-	-	pF

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

[2] Typical values are measured at  $V_{CC} = 3.3\text{ V}$ .

[3] Typical values are measured at  $V_{CC} = 5.0\text{ V}$ .

[4]  $C_{PD}$  is used to determine the dynamic power dissipation  $P_D$  ( $\mu\text{W}$ ).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

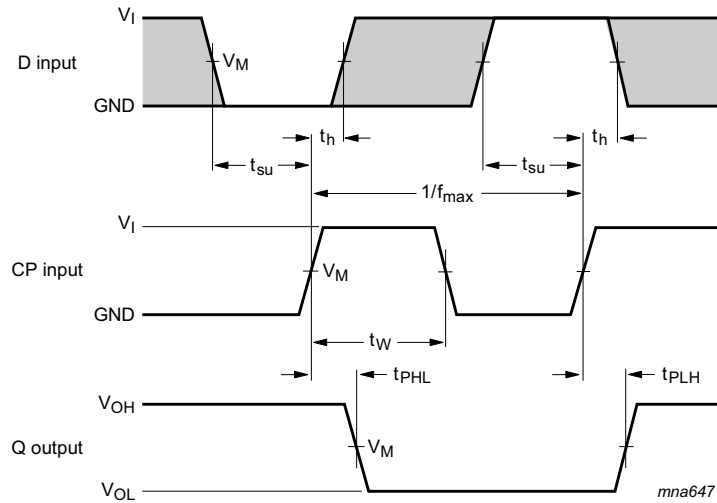
$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts.

12. Waveforms

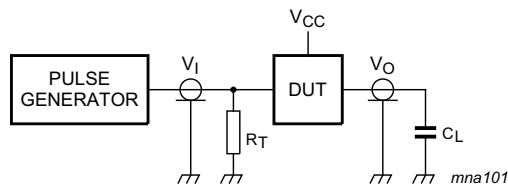


Measurement points are given in [Table 9](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output.

**Fig 5. Clock (CP) to output (Q) propagation delay times, clock pulse width, D to set-up times, the CP to D hold times and maximum clock pulse frequency**

**Table 9. Measurement points**

Type	Inputs		Output
	$V_I$	$V_M$	$V_M$
74AHC1G79	GND to $V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74AHCT1G79	GND to 3.0 V	1.5 V	$0.5 \times V_{CC}$



Test data is given in [Table 8](#). Definitions for test circuit:  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

**Fig 6. Test circuit for measuring switching times**



13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

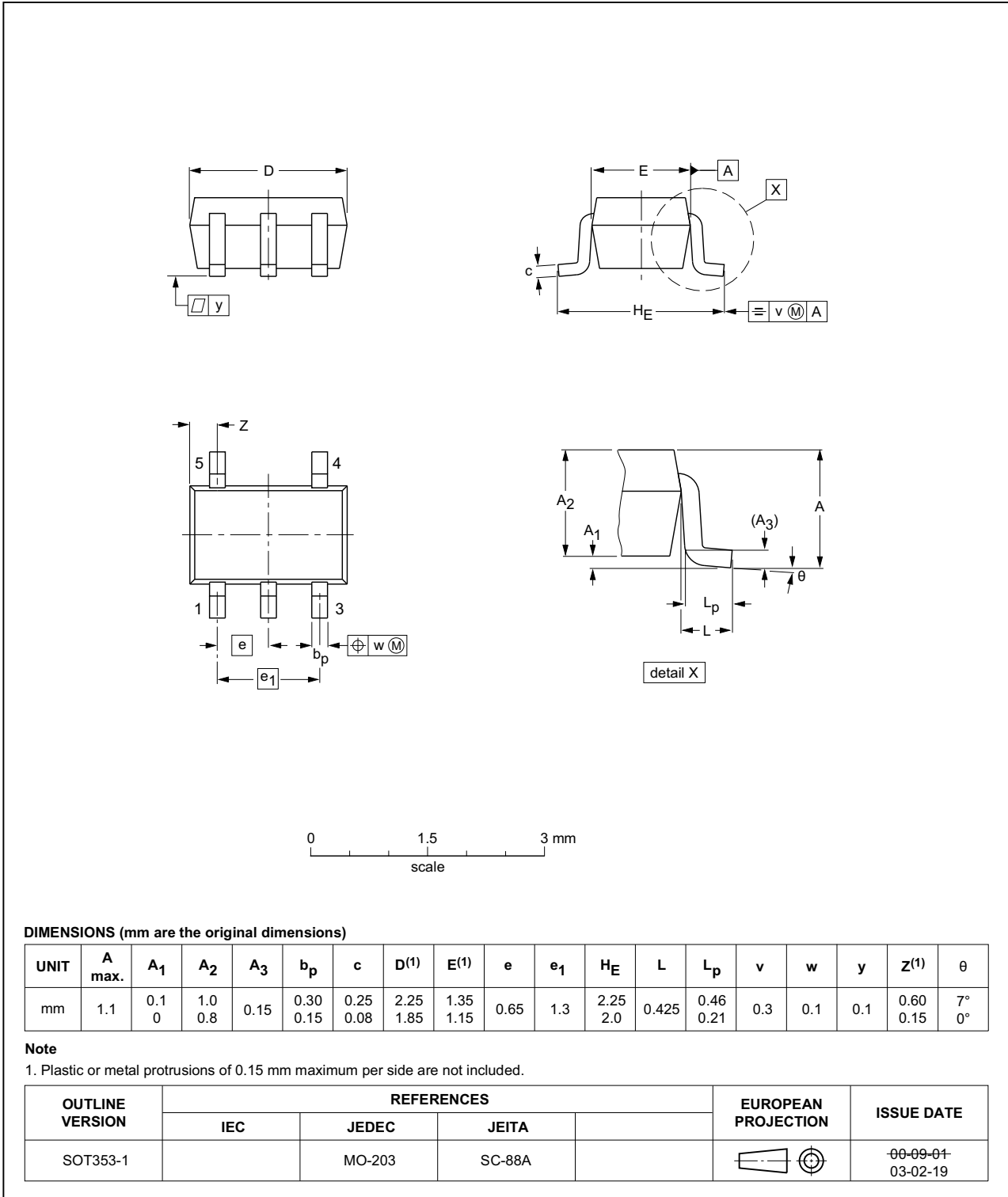


Fig 7. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

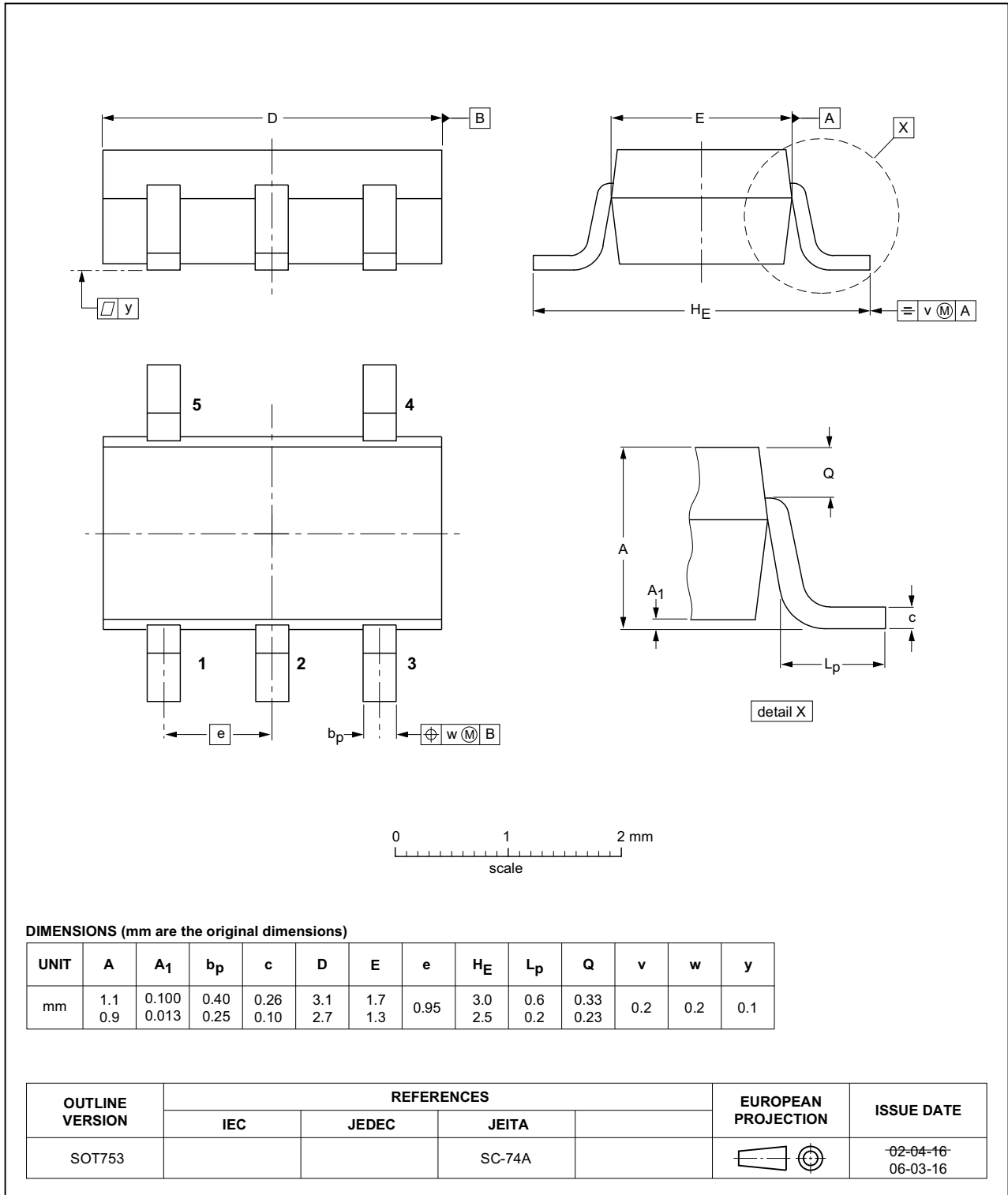


Fig 8. Package outline SOT753 (SC-74A)

## 14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT1G79 v.6	20140923	Product data sheet	-	74AHC_AHCT1G79 v.5
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Section 4</a>: table note added.</li> </ul>			
74AHC_AHCT1G79 v.5	20070702	Product data sheet	-	74AHC_AHCT1G79 v.4
74AHC_AHCT1G79 v.4	20020606	Product specification	-	74AHC_AHCT1G79 v.3
74AHC_AHCT1G79 v.3	20020218	Product specification	-	74AHC_AHCT1G79 v.2
74AHC_AHCT1G79 v.2	20010222	Product specification	-	74AHC_AHCT1G79 v.1
74AHC_AHCT1G79 v.1	19990518	Product specification	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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